as allegedly being anticipated by U.S. Patent No. 6,042,389 (Lemke et al.). Applicant's undersigned attorney respectfully requests reconsideration of the present application in view of the above amendments and following remarks.

Information Disclosure Statement

Applicant previously submitted an Information Disclosure Statement and Form 1449 on September 5, 2001. A signed copy of the Form 1449 has not been received. Applicant's undersigned attorney respectfully requests that the Examiner return a signed copy of the Form 1449 submitted on September 5, 2001 with the next communication.

Rejection Under 35 U.S.C. § 112

Claim 33 stands rejected under 35 U.S.C. § 112 as allegedly failing to particularly point out and distinctly claim the subject matter of the invention. Applicant proposes amending claim 33 to clarify the claim language. Accordingly, withdrawal of the rejection is respectfully solicited.

Rejection Under 35 U.S.C. § 102(e)

Claims 33 through 35 stand rejected under 35 U.S.C. 102(e) as allegedly being anticipated by U.S. Patent No. 6,042,389 (Lemke et al.). Applicant's undersigned attorney respectfully submits that the claims patentably define over Lemke et al.

Claim 33 is directed to an electrical connector assembly comprising:

"a first connector half, said first connector half having first and second surfaces, said first surface having an array of reflowable connecting elements thereon for electrical and mechanical connection to mating corresponding elements already on said substrate, said second surface having a first array of frictional connecting elements, said reflowable connecting elements connected to said first array of frictional connecting elements; and

a second connector half, said second connector half having first and second surfaces, said first surface having an array of mounting elements thereon for electrical and mechanical connection to reflowable mating elements already on said component, said second surface having a second array of frictional connecting elements, said mounting elements connected to said second array of frictional connecting elements."

Thus, the claimed invention requires a first connector half with reflowable mating elements for connection to a substrate and a second connector having mounting elements for connection with reflowable mating elements already on a component. Applicant's undersigned attorney respectfully submits that Lemke et al. do not teach or even suggest this claimed combination.

Lemke et al. disclose a "low profile board to board connector system." (Abstract). The connector system comprises a plug connector 20 and a receptacle 52. (See Fig. 4). Plug connector 20 has solder balls 35 along its external side for connection to a circuit board. (See Figs. 4 and 5). Similarly, receptacle 52 has solder balls 74 along its external side for connection to a circuit board. (See Figs. 4 and 5). Thus, Lemke et al. teach a connector system wherein both connector halves have solder balls, i.e. reflowable mating elements, for mating with external components. In contradistinction, the claims require "a second connector half… having an array of mounting elements thereon for electrical and

mechanical connection to reflowable mating elements already on said component."

Lemke et al. entirely fail to teach or suggest that one of its halves have mounting elements for connection to reflowable mating elements already on a component. Indeed, by teaching that both connector halves themselves have reflowable mating elements, i.e. solder balls, Lemke et al. actually teach away from a connector that accommodates reflowable mating elements already on an electrical component.

Therefore, because they do not teach a connector half "having an array of mounting elements thereon for electrical and mechanical connection to reflowable mating elements already on said component," Lemke et al. cannot possibly anticipate the claimed invention. Furthermore, none of the other cited references teach or suggest the claimed combination of elements. Accordingly, Applicant's undersigned attorney respectfully requests withdrawal of the rejections under 35 U.S.C. § 102.

CONCLUSION

Applicant respectfully submit that claims 33 through 35 patentably define over the prior art of record. Reconsideration of the present Office Action and a Notice of Allowance are respectfully requested.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In accordance with 37 C.F.R. § 1.121, below is a copy of claim 33.

33. (amended) An electrical connector assembly adapted for forming a mechanical and an electrical connection between a component and a substrate and absorbing <u>differences</u> in CTE between said component and said substrate, said connector assembly comprising:

a first connector half, said first connector half having first and second surfaces, said first surface having an array of reflowable connecting elements thereon for electrical and mechanical connection to mating corresponding elements <u>already</u> on said substrate, said second surface having [an] <u>a first</u> array of frictional connecting elements, said reflowable connecting elements connected to said <u>first array of frictional connecting elements</u>; and

a second connector half, said second connector half having first and second surfaces, said first surface having an array of [connecting] mounting elements thereon for electrical and mechanical connection to reflowable mating elements already on said component, said second surface having [an] a second array of frictional connecting elements, said [reflowable connecting] mounting elements connected to said second array of frictional connecting elements;

wherein mating said frictional contacting elements of said first and second connector halves electrically connects said component to said substrate, said first and second frictional contacting elements constructed such that when mated there can still be at least some relative movement between the two along at least two axes to allow for <u>differences in</u> CTE [to be absorbed] between said component and said substrate to be absorbed.